

NL27WZ16

Dual Buffer

The NL27WZ16 is a high performance dual buffer operating from a 1.65 to 5.5 V supply. At $V_{CC} = 3$ V, high impedance TTL compatible inputs significantly reduce current loading to input drivers while TTL compatible outputs offer improved switching noise performance.

Features

- Extremely High Speed: t_{PD} 2.0 ns (typical) at $V_{CC} = 5$ V
- Designed for 1.65 V to 5.5 V V_{CC} Operation
- Over Voltage Tolerant Inputs
- LVTTL Compatible – Interface Capability With 5 V TTL Logic with $V_{CC} = 3$ V
- LVC MOS Compatible
- 24 mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current Substantially Reduces System Power Requirements
- Chip Complexity: FET = 72; Equivalent Gate = 18
- Pb-Free Packages are Available

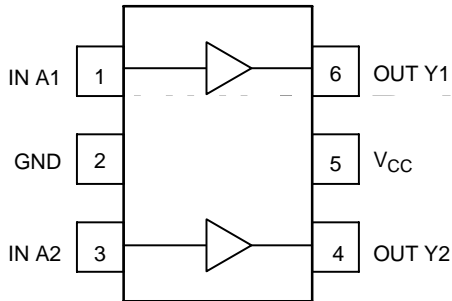


Figure 1. Pinout (Top View)

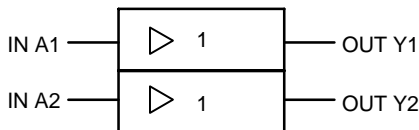


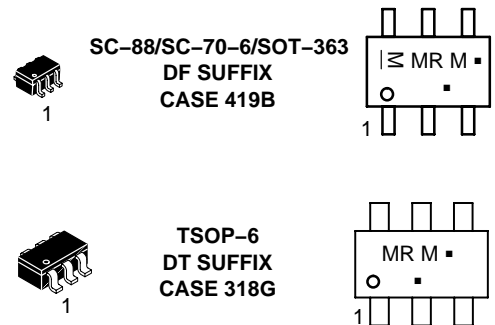
Figure 2. Logic Symbol



ON Semiconductor®

<http://onsemi.com>

MARKING DIAGRAMS



MR = Device Code
M = Date Code*
▪ = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or position and underbar may vary depending upon manufacturing location.

PIN ASSIGNMENT

1	IN A1
2	GND
3	IN A2
4	OUT Y2
5	V_{CC}
6	OUT Y1

FUNCTION TABLE

A Input	Y Output
L	L
H	H

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

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MAXIMUM RATINGS

Characteristics	Symbol	Value	Unit
DC Supply Voltage	V_{CC}	-0.5 to +7.0	V
DC Input Voltage	V_I	$-0.5 \leq V_I \leq +7.0$	V
DC Output Voltage	Output in Z or LOW State (Note 1) V_O	$-0.5 \leq V_O \leq 7.0$	V
DC Input Diode Current	$V_I < \text{GND}$ I_{IK}	-50	mA
DC Output Diode Current	$V_O < \text{GND}$ I_{OK}	-50	mA
DC Output Sink Current	I_O	± 50	mA
DC Supply Current per Supply Pin	I_{CC}	± 100	mA
DC Ground Current per Ground Pin	I_{GND}	± 100	mA
Storage Temperature Range	T_{STG}	-65 to +150	°C
Power Dissipation in Still Air	SC-88, TSOP-6 P_D	200	mW
Thermal Resistance	SC-88, TSOP-6 θ_{JA}	333	°C/W
Lead Temperature, 1 mm from Case for 10 Seconds	T_L	260	°C
Junction Temperature Under Bias	T_J	+150	°C
ESD Withstand Voltage	Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4) V_{ESD}	> 2000 > 200 N/A	V
Latchup Performance	Above V_{CC} and Below GND at 85°C (Note 5) $I_{Latchup}$	± 500	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. I_O absolute maximum rating must be observed.
2. Tested to EIA/JESD22-A114-A
3. Tested to EIA/JESD22-A115-A
4. Tested to JESD22-C101-A
5. Tested to EIA/JESD78

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Min	Max	Unit
Supply Voltage	Operating Data Retention Only V_{CC}	1.65 1.5	5.5 5.5	V
Input Voltage	V_I	0	5.5	V
Output Voltage	(High or LOW State) V_O	0	5.5	V
Operating Free-Air Temperature	T_A	-40	+85	°C
Input Transition Rise or Fall Rate	$V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$ $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$ $V_{CC} = 3.0 \text{ V} \pm 0.3 \text{ V}$ $V_{CC} = 5.0 \text{ V} \pm 0.5 \text{ V}$ $\Delta t/\Delta V$	0 0 0 0	20 20 10 5	ns/V

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DC ELECTRICAL CHARACTERISTICS

Parameter	Condition	Symbol	V _{CC} (V)	T _A = 25°C			-40°C ≤ T _A ≤ 85°C		Unit
				Min	Typ	Max	Min	Max	
High-Level Input Voltage		V _{IH}	1.65 to 1.95 2.3 to 5.5	0.75 V _{CC} 0.7 V _{CC}			0.75 V _{CC} 0.7 V _{CC}		V
Low-Level Input Voltage		V _{IL}	1.65 to 1.95 2.3 to 5.5			0.25 V _{CC} 0.3 V _{CC}		0.25 V _{CC} 0.3 V _{CC}	V
High-Level Output Voltage V _{IN} = V _{IH}	I _{OH} = -100 μA	V _{OH}	1.65 1.8 2.3 3.0 4.5	1.55 1.7 2.2 2.9 4.4	1.65 1.8 2.3 3.0 4.5		1.55 1.7 2.2 2.9 4.4		V
	I _{OH} = -4 mA I _{OH} = -8 mA I _{OH} = -16 mA I _{OH} = -24 mA I _{OH} = -32 mA		1.65 2.3 3.0 3.0 4.5	1.29 1.9 2.4 2.3 3.8	1.52 2.15 2.80 2.68 4.20		1.29 1.9 2.4 2.3 3.8		V
Low-Level Output Voltage V _{IN} = V _{IL}	I _{OL} = 100 μA	V _{OL}	1.65 1.8 2.3 3.0 4.5		0.0 0.0 0.0 0.0 0.0	0.1 0.1 0.1 0.1 0.1		0.1 0.1 0.1 0.1 0.1	V
	I _{OL} = 4 mA I _{OL} = 8 mA I _{OL} = 16 mA I _{OL} = 24 mA I _{OL} = 32 mA		1.65 2.3 3.0 3.0 4.5		0.08 0.10 0.15 0.22 0.22	0.24 0.30 0.40 0.55 0.55		0.24 0.30 0.40 0.55 0.55	V
Input Leakage Current	0 V ≤ V _{IN} ≤ 5.5 V	I _{IN}	0 to 5.5			± 1.0		± 1.0	μA
Power Off Leakage Current	V _{IN} or V _{OUT} = 5.5 V	I _{OFF}	0.0			1.0		10	μA
Quiescent Supply Current	V _{IN} = 5.5 V, GND	I _{CC}	1.65 to 5.5			1.0		10	μA

AC ELECTRICAL CHARACTERISTICS t_R = t_F = 2.5 ns; C_L = 50 pF; R_L = 500 Ω

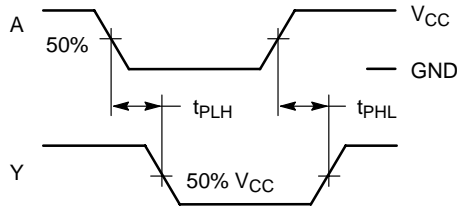
Parameter	Condition	Symbol	V _{CC} (V)	T _A = 25°C			-40°C ≤ T _A ≤ 85°C		Unit
				Min	Typ	Max	Min	Max	
Propagation Delay (Figure 3 and 4)	R _L = 1 MΩ, C _L = 15 pF	t _{PLH} t _{PHL}	1.8 ± 0.15	1.8	8.0	9.6	1.8	10.2	ns
	R _L = 1 MΩ, C _L = 15 pF			2.5 ± 0.2	1.0	3.0	5.2	1.0	
	R _L = 1 MΩ, C _L = 15 pF	3.3 ± 0.3	0.8	2.3	3.6	0.8	4.0		
	R _L = 500 Ω, C _L = 50 pF		1.2	3.0	4.6	1.2	5.1		
	R _L = 1 MΩ, C _L = 15 pF	5.0 ± 0.5	0.5	1.8	2.9	0.5	3.2		
	R _L = 500 Ω, C _L = 50 pF		0.8	2.4	3.8	0.8	4.2		

CAPACITIVE CHARACTERISTICS

Parameter	Condition	Symbol	Typical	Unit
Input Capacitance	V _{CC} = 5.5 V, V _I = 0 V or V _{CC}	C _{IN}	7.0	pF
Power Dissipation Capacitance (Note 6)	10 MHz, V _{CC} = 3.3 V, V _I = 0 V or V _{CC} 10 MHz, V _{CC} = 5.5 V, V _I = 0 V or V _{CC}	C _{PD}	9 11	pF

6. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no-load dynamic power consumption; P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.

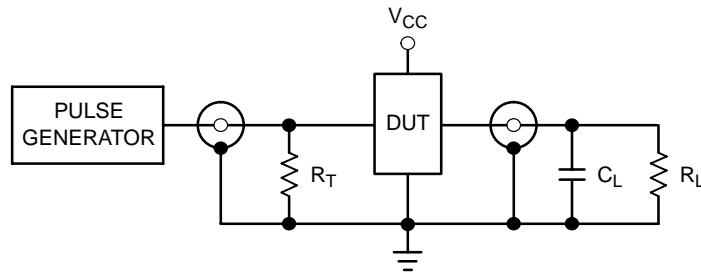
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PROPAGATION DELAYS

$t_R = t_F = 2.5$ ns, 10% to 90%; $f = 1$ MHz; $t_W = 500$ ns

Figure 3. Switching Waveforms



$R_T = Z_{OUT}$ of pulse generator (typically 50 Ω)

Figure 4. Test Circuit

ORDERING INFORMATION

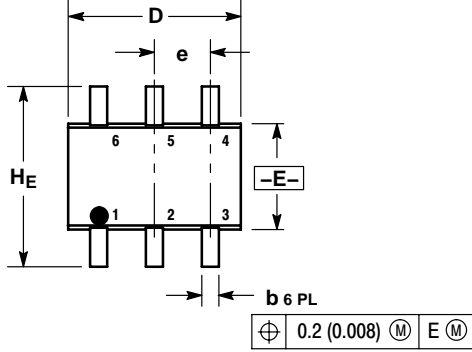
Device	Package	Shipping [†]
NL27WZ16DFT2	SC-88/SC-70/SOT-363	3000 /Tape & Reel
NL27WZ16DFT2G	SC-88/SC-70/SOT-363 (Pb-Free)	
NL27WZ16DTT1	TSOP-6	
NL27WZ16DTT1G	TSOP-6 (Pb-Free)	

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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PACKAGE DIMENSIONS

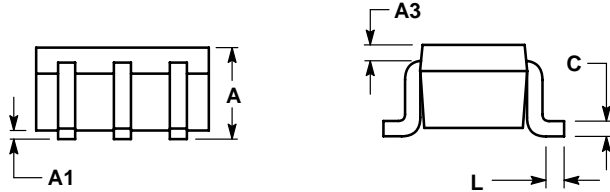
SC-88/SC70-6/SOT-363
CASE 419B-02
ISSUE W



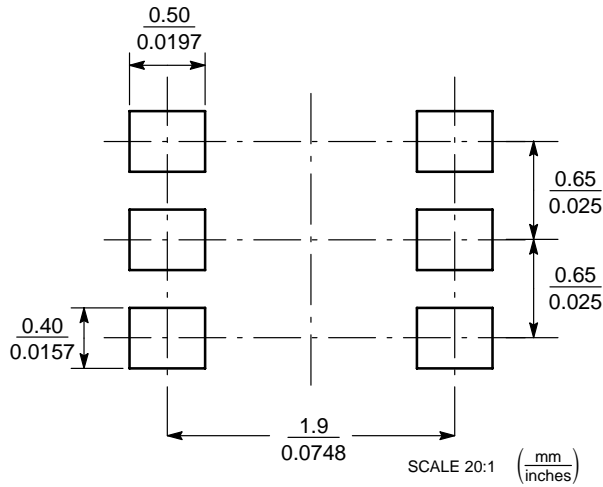
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. 419B-01 OBSOLETE, NEW STANDARD 419B-02.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	0.95	1.10	0.031	0.037	0.043
A1	0.00	0.05	0.10	0.000	0.002	0.004
A3	0.20 REF			0.008 REF		
b	0.10	0.21	0.30	0.004	0.008	0.012
C	0.10	0.14	0.25	0.004	0.005	0.010
D	1.80	2.00	2.20	0.070	0.078	0.086
E	1.15	1.25	1.35	0.045	0.049	0.053
e	0.65 BSC			0.026 BSC		
L	0.10	0.20	0.30	0.004	0.008	0.012
HE	2.00	2.10	2.20	0.078	0.082	0.086



SOLDERING FOOTPRINT*

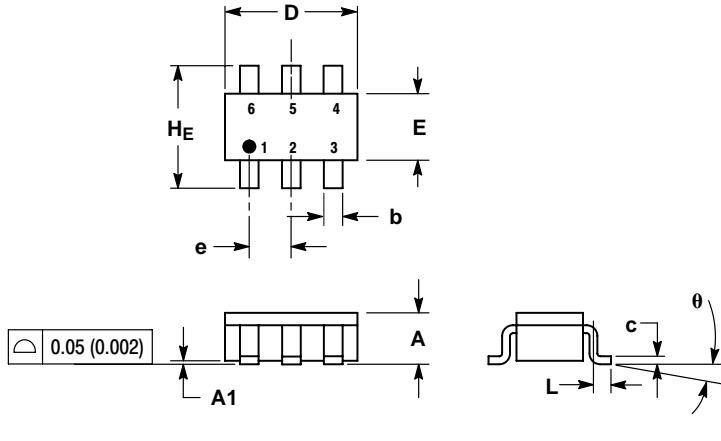


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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PACKAGE DIMENSIONS

TSOP-6 CASE 318G-02 ISSUE S

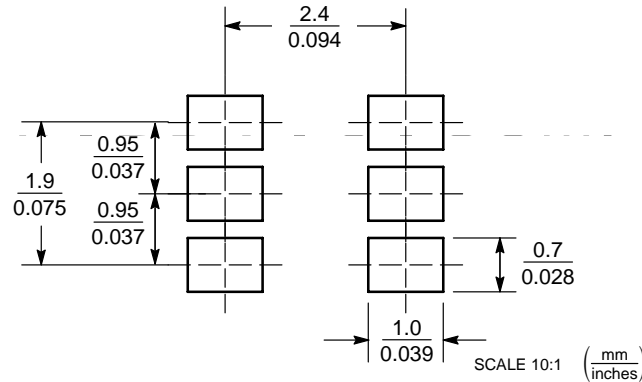


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.90	1.00	1.10	0.035	0.039	0.043
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.25	0.38	0.50	0.010	0.014	0.020
c	0.10	0.18	0.26	0.004	0.007	0.010
D	2.90	3.00	3.10	0.114	0.118	0.122
E	1.30	1.50	1.70	0.051	0.059	0.067
e	0.85	0.95	1.05	0.034	0.037	0.041
L	0.20	0.40	0.60	0.008	0.016	0.024
HE	2.50	2.75	3.00	0.099	0.108	0.118
theta	0°	-	10°	0°	-	10°

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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